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ON Semiconductor®

FQP50N06L

N-Channel QFET® MOSFET **60 V, 52.4 A, 21 m**Ω

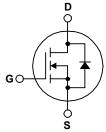
Description

This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- 52.4 A, 60 V, $R_{DS(on)}$ = 21 m Ω (Max.) @ V_{GS} = 10 V, $I_D = 26.2 A$
- Low Gate Charge (Typ. 24.5 nC)
- Low Crss (Typ. 90 pF)
- 100% Avalanche Tested
- 175°C Maximum Junction Temperature Rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQP50N06L	Unit
V _{DSS}	Drain-Source Voltage		60	V
I _D	Drain Current - Continuous (T _C = 25°	C)	52.4	Α
	- Continuous (T _C = 100)°C)	37.1	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	210	Α
V _{GSS}	Gate-Source Voltage		± 20	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	990	mJ
I _{AR}	Avalanche Current	(Note 1)	52.4	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	12.1	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P_D	Power Dissipation (T _C = 25°C)		121	W
	- Derate above 25°C		0.81	W/°C
T _J , T _{STG}	Operating and Storage Temperature Rar	nge	-55 to +175	°C
T _L	Maximum Lead Temperature for Solderin 1/8" from Case for 5 seconds	ng,	300	°C

Thermal Characteristics

Symbol	Parameter	FQP50N06L	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	1.24	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP50N06L	FQP50N06L	TO-220	Tube	N/A	N/A	50 units

FI	lactrica	l Chara	acteristics
	iecuica	ı Gilala	46161151165

 $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	60			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.06		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 48 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.5	V
R _{DS(on)}	Static Drain-Source	V_{GS} = 10 V, I_{D} = 26.2 A		0.017	0.021	Ω
	On-Resistance	$V_{GS} = 5 \text{ V}, I_D = 26.2 \text{ A}$		0.020	0.025	52
9 _{FS}	Forward Transconductance	V _{DS} = 25 V, I _D = 26.2 A		40		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	 1250	1630	pF
Coss	Output Capacitance	f = 1.0 MHz	 445	580	pF
C _{rss}	Reverse Transfer Capacitance		 90	120	pF

Switching Characteristics

	9				
t _{d(on)}	Turn-On Delay Time	V _{DD} = 30 V, I _D = 26.2 A,	 20	50	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	 380	770	ns
t _{d(off)}	Turn-Off Delay Time	1.6 = 1.2	 80	170	ns
t _f	Turn-Off Fall Time	(Note 4)	 145	300	ns
Q_g	Total Gate Charge	V _{DS} = 48 V, I _D = 52.4 A,	 24.5	32	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 5 V	 6		nC
Q _{gd}	Gate-Drain Charge	(Note 4)	 14.5		nC

Drain-Source Diode Characteristics and Maximum Ratings

Is	Maximum Continuous Drain-Source Diode Forward Current		 	52.4	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		 	210	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 52.4 A	 	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 52.4 A,	 65		ns
Q _{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/μs	 125		nC

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 300 μ H, I_{AS} = 52.4 A, V_{DD} = 25 V, R_G = 25 Ω , starting T_J = 25°C. 3. I_{SD} \leq 52.4 A, di/dt \leq 300 A/ μ s, V_{DD} \leq BV_{DSS}, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

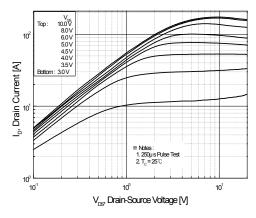


Figure 1. On-Region Characteristics

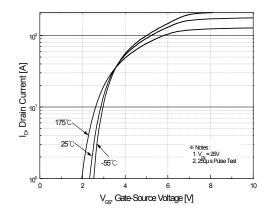


Figure 2. Transfer Characteristics

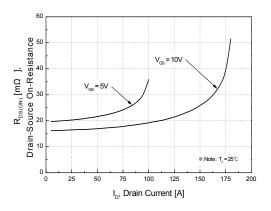


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

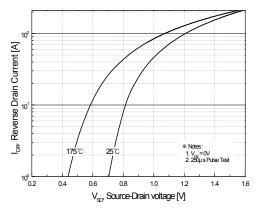


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

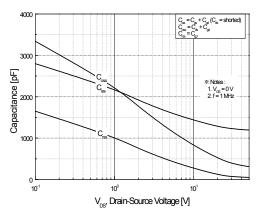


Figure 5. Capacitance Characteristics

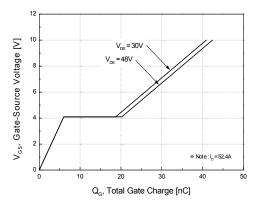


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)

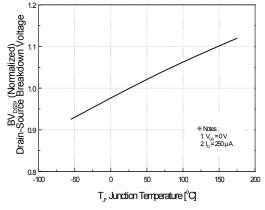


Figure 7. Breakdown Voltage Variation vs. Temperature

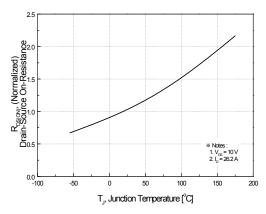


Figure 8. On-Resistance Variation vs. Temperature

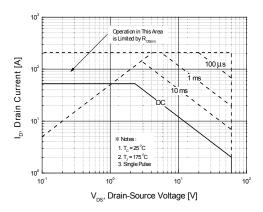


Figure 9. Maximum Safe Operating Area

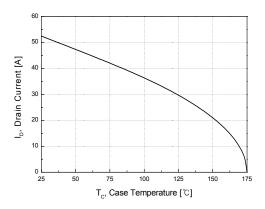


Figure 10. Maximum Drain Current vs. Case Temperature

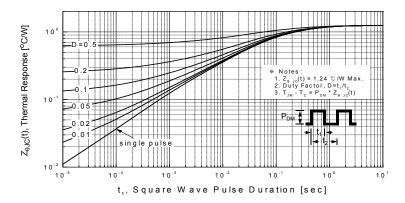


Figure 11. Transient Thermal Response Curve

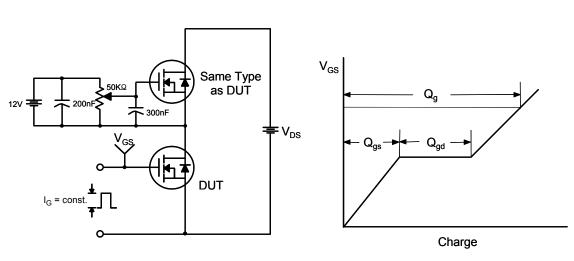


Figure 12. Gate Charge Test Circuit & Waveform

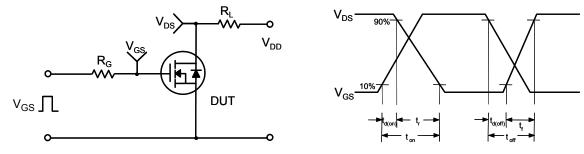


Figure 13. Resistive Switching Test Circuit & Waveforms

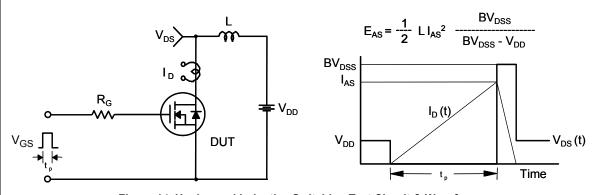
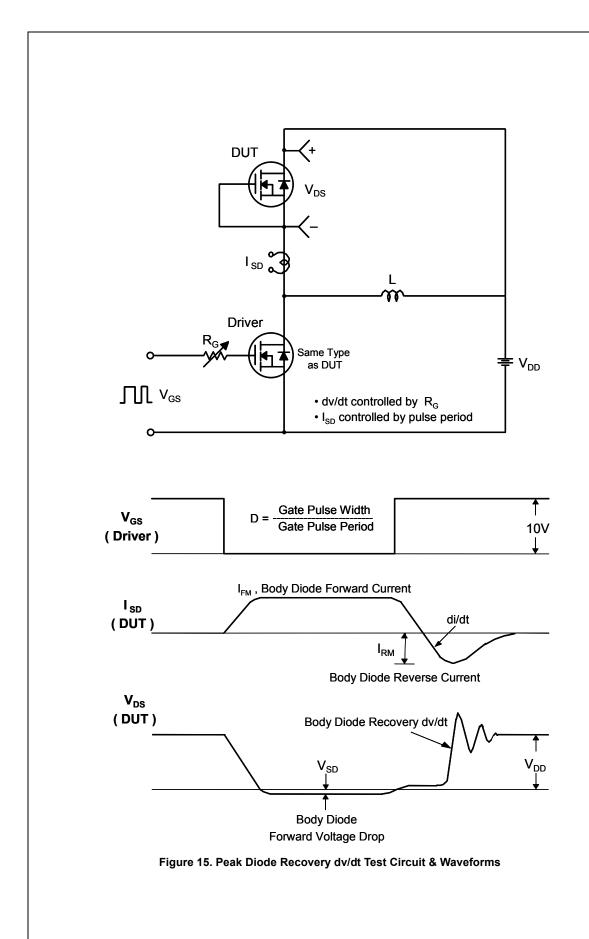
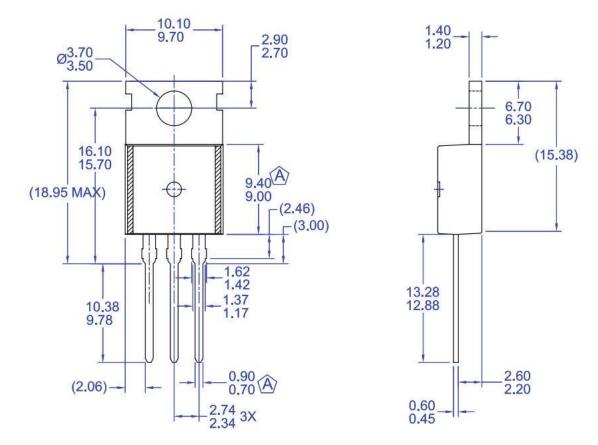
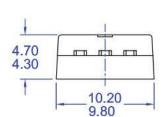


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions





NOTES:

- (A) CONFORMS TO JEDEC TO-220 VARIATION AB EXCEPT WHERE NOTED
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DRAWING FILE/REVISION: MKT-TO220Y03REV1

Figure 16. TO220, Molded, 3-Lead, Jedec Variation AB

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